### MKP Film Capacitor

**Material Data Sheet**

<table>
<thead>
<tr>
<th>Product Class</th>
<th>Motor run round B32328* /B32356*</th>
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<tbody>
<tr>
<td><strong>Date</strong></td>
<td>18/11/2019</td>
</tr>
<tr>
<td><strong>IMDS ID</strong></td>
<td>NA</td>
</tr>
<tr>
<td><strong>Version</strong></td>
<td>5.02.1a (03/2019)</td>
</tr>
</tbody>
</table>

#### Active Part
- **Thermoplastic**: 2A PP 100, 9003-07-0, 30.4
- **Light Metal**: 1B Al 6, 7429-90-5, 1.3
- **Heavy Metal**: 1C Zn 94, 7440-66-6, 10.4

#### Encapsulation
- **Thermoplastic**: 2A PA 66 or PA6 100, 32131-17-2 or 25038-54-4, 13.3
- **Melamine Cynurate**: 50, 37640-57-6
- **Durometer**: 2D Epoxy resin / PU resin 100, Not available, 26.6

#### Termination
- **Heavy Metal**: 1C Sn 99.3, 7440-31-5, 0.8
- **Cu 0.7**: 7440-50-8, 0.1
- **Heavy Metal**: 1C Cu 100, 7440-50-8, 4.1
- **Thermoplastic**: 2A PVC 100, 9002-86-2, 12.2 or 13
- **Heavy Metal**: 1C Brass (Optional) 100, 7440-31-5, 0.8

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**Sum in total**: 100

**sizes (DxH)**: 25x56 48, 66 83, 75 134
**part numbers**: B32328* 30x56 48, B32356* 35x73 93, 40x85 134

**weight range (g)**: 40 93, 96 134

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**Not part of a Product Class**

**Contact**
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**Important remarks**:

1) The declaration limit is 0.1% as defined by IEC PAS 61906. Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.

2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.

***) others: (not declarable or prohibited substances acc. GADSL)

**'** typical mass percentage of substance

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The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.
### RoHS - Exemptions for the Product Class / Product according to Annex III:

- **no exemptions;**
- ☐ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight;
- ☐ Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight;
- ☐ Exemption 6 (c): Copper alloy containing up to 4% lead by weight;
- ☐ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 65% by weight or more lead);
- ☐ Exemption 7 (b): Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- ☐ Exemption 7 (c): Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- ☐ Exemption 7 (d): Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- ☐ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- ☐ Other Exception than above ............................................................